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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	M8C
Core Size	8-Bit
Speed	12MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	24
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.25V
Data Converters	A/D 12x14b; D/A 4x9b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/cy8c29466-12pvxet">https://www.e-xfl.com/product-detail/infineon-technologies/cy8c29466-12pvxet</a>

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## Development Tools

PSoC Designer™ is the revolutionary integrated design environment (IDE) that you can use to customize PSoC to meet your specific application requirements. PSoC Designer software accelerates system design and time to market. Develop your applications using a library of precharacterized analog and digital peripherals (called user modules) in a drag-and-drop design environment. Then, customize your design by leveraging the dynamically generated application programming interface (API) libraries of code. Finally, debug and test your designs with the integrated debug environment, including in-circuit emulation and standard software debug features. PSoC Designer includes:

- Application editor graphical user interface (GUI) for device and user module configuration and dynamic reconfiguration
- Extensive user module catalog
- Integrated source-code editor (C and assembly)
- Free C compiler with no size restrictions or time limits
- Built-in debugger
- In-circuit emulation
- Built-in support for communication interfaces:
  - Hardware and software I<sup>2</sup>C slaves and masters
  - Full-speed USB 2.0
  - Up to four full-duplex universal asynchronous receiver/transmitters (UARTs), SPI master and slave, and wireless

PSoC Designer supports the entire library of PSoC 1 devices and runs on Windows XP, Windows Vista, and Windows 7.

### PSoC Designer Software Subsystems

#### *Design Entry*

In the chip-level view, choose a base device to work with. Then select different onboard analog and digital components that use the PSoC blocks, which are called user modules. Examples of user modules are ADCs, DACs, amplifiers, and filters. Configure the user modules for your chosen application and connect them to each other and to the proper pins. Then generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration makes it possible to change configurations at run time. In essence, this allows you to use more than 100 percent of PSoC's resources for an application.

#### *Code Generation Tools*

The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. You can develop your design in C, assembly, or a combination of the two.

**Assemblers.** The assemblers allow you to merge assembly code seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and are linked with other software modules to get absolute addressing.

**C Language Compilers.** C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices. The optimizing C compilers provide all of the features of C, tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

#### *Debugger*

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow you to read and program and read and write data memory, and read and write I/O registers. You can read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also allows you to create a trace buffer of registers and memory locations of interest.

#### *Online Help System*

The online help system displays online, context-sensitive help. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an online support Forum to aid the designer.

#### *In-Circuit Emulator*

A low-cost, high-functionality in-circuit emulator (ICE) is available for development support. This hardware can program single devices.

The emulator consists of a base unit that connects to the PC using a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full-speed (24 MHz) operation.

## Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC Blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is summarized in four steps:

1. Select [User Modules](#).
2. Configure User Modules.
3. Organize and Connect.
4. Generate, Verify, and Debug.

### Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called "user modules." User modules make selecting and implementing peripheral devices, both analog and digital, simple.

## Pinouts

The automotive CY8C29x66 PSoC device is available in a variety of packages which are listed and illustrated in the following tables. Every port pin (labeled with a “P”) is capable of Digital I/O. However, Vss, Vdd, and XRES are not capable of Digital I/O.

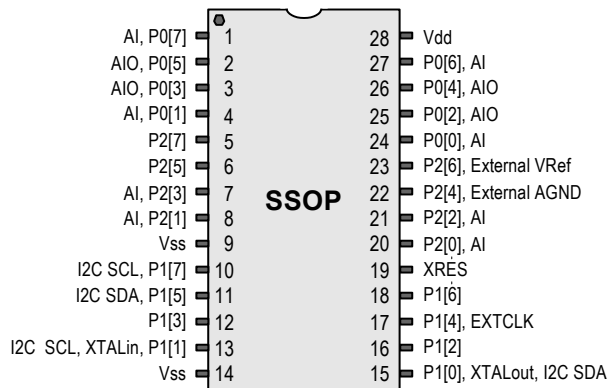
### 28-pin Part Pinout

**Table 2. 28-Pin Part Pinout (SSOP)**

Pin No.	Type		Pin Name	Description
	Digital	Analog		
1	I/O	I	P0[7]	Analog column mux input.
2	I/O	I/O	P0[5]	Analog column mux input and column output.
3	I/O	I/O	P0[3]	Analog column mux input and column output.
4	I/O	I	P0[1]	Analog column mux input.
5	I/O		P2[7]	
6	I/O		P2[5]	
7	I/O	I	P2[3]	Direct switched capacitor block input.
8	I/O	I	P2[1]	Direct switched capacitor block input.
9	Power		Vss	Ground connection.
10	I/O		P1[7]	I <sup>2</sup> C Serial Clock (SCL).
11	I/O		P1[5]	I <sup>2</sup> C Serial Data (SDA).
12	I/O		P1[3]	
13	I/O		P1[1]	Crystal Input (XTALin), I <sup>2</sup> C Serial Clock (SCL), ISSP-SCLK <sup>5</sup> .
14	Power		Vss	Ground connection.
15	I/O		P1[0]	Crystal Output (XTALout), I <sup>2</sup> C Serial Data (SDA), ISSP-SDATA <sup>5</sup> .
16	I/O		P1[2]	
17	I/O		P1[4]	Optional External Clock Input (EXTCLK).
18	I/O		P1[6]	
19	Input		XRES	Active high external reset with internal pull down.
20	I/O	I	P2[0]	Direct switched capacitor block input.
21	I/O	I	P2[2]	Direct switched capacitor block input.
22	I/O		P2[4]	External Analog Ground (AGND).
23	I/O		P2[6]	External Voltage Reference (VRef).
24	I/O	I	P0[0]	Analog column mux input.
25	I/O	I/O	P0[2]	Analog column mux input and column output.
26	I/O	I/O	P0[4]	Analog column mux input and column output.
27	I/O	I	P0[6]	Analog column mux input.
28	Power		Vdd	Supply voltage.

**LEGEND:** A = Analog, I = Input, and O = Output.

**Figure 3. CY8C29466 28-pin PSoC Device**



#### Note

5. These are the ISSP pins, which are not High Z when coming out of POR (Power On Reset). See the [PSoC Technical Reference Manual](#) for details.

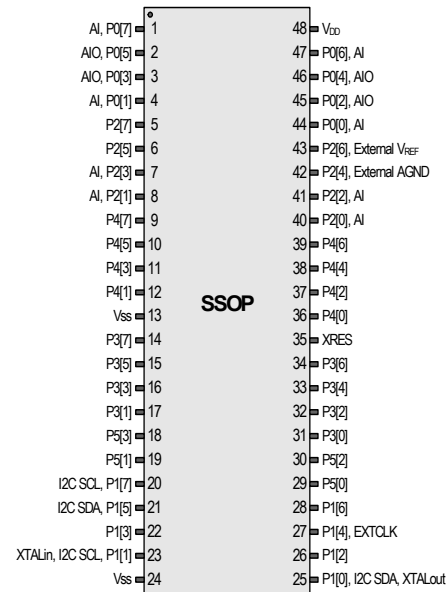
## 48-pin Part Pinout

**Table 3. 48-pin Part Pinout (SSOP)**

Pin No.	Type		Pin Name	Description
	Digital	Analog		
1	I/O	I	P0[7]	Analog column mux input
2	I/O	I/O	P0[5]	Analog column mux input and column output
3	I/O	I/O	P0[3]	Analog column mux input and column output
4	I/O	I	P0[1]	Analog column mux input
5	I/O		P2[7]	
6	I/O		P2[5]	
7	I/O	I	P2[3]	Direct switched capacitor block input
8	I/O	I	P2[1]	Direct switched capacitor block input
9	I/O		P4[7]	
10	I/O		P4[5]	
11	I/O		P4[3]	
12	I/O		P4[1]	
13	Power		V <sub>SS</sub>	Ground connection
14	I/O		P3[7]	
15	I/O		P3[5]	
16	I/O		P3[3]	
17	I/O		P3[1]	
18	I/O		P5[3]	
19	I/O		P5[1]	
20	I/O		P1[7]	I <sup>2</sup> C serial clock (SCL)
21	I/O		P1[5]	I <sup>2</sup> C serial data (SDA)
22	I/O		P1[3]	
23	I/O		P1[1]	Crystal input (XTALin), I <sup>2</sup> C serial clock (SCL), ISSP-SCLK <sup>[6]</sup>
24	Power		V <sub>SS</sub>	Ground connection
25	I/O		P1[0]	Crystal output (XTALout), I <sup>2</sup> C Serial Data (SDA), ISSP-SDATA <sup>[6]</sup>
26	I/O		P1[2]	
27	I/O		P1[4]	Optional external clock (EXTCLK) input
28	I/O		P1[6]	
29	I/O		P5[0]	
30	I/O		P5[2]	
31	I/O		P3[0]	
32	I/O		P3[2]	
33	I/O		P3[4]	
34	I/O		P3[6]	
35	Input		XRES	Active high external reset with internal pull-down
36	I/O		P4[0]	
37	I/O		P4[2]	
38	I/O		P4[4]	
39	I/O		P4[6]	
40	I/O	I	P2[0]	Direct switched capacitor block input
41	I/O	I	P2[2]	Direct switched capacitor block input
42	I/O		P2[4]	External analog ground (AGND)
43	I/O		P2[6]	External voltage reference (V <sub>REF</sub> )
44	I/O	I	P0[0]	Analog column mux input
45	I/O	I/O	P0[2]	Analog column mux input and column output
46	I/O	I/O	P0[4]	Analog column mux input and column output
47	I/O	I	P0[6]	Analog column mux input
48	Power		V <sub>DD</sub>	Supply voltage

**LEGEND:** A = Analog, I = Input, and O = Output.

**Figure 4. CY8C29666 48-pin PSoC Device**



### Note

6. These are the ISSP pins, which are not high Z when coming out of POR. See the *PSoC Technical Reference Manual* for details.

## Registers

### Register Conventions

This section lists the registers of the automotive CY8C29x66 PSoC device. For detailed register information, reference the [PSoC Technical Reference Manual](#).

The register conventions specific to this section are listed in the following table.

**Table 4. Abbreviations**

Convention	Description
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
C	Clearable register or bit(s)
#	Access is bit specific

### Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks. The XIO bit in the Flag register (CPU\_F) determines which bank the user is currently in. When the XIO bit is set the user is in Bank 1.

**Note** In the following register mapping tables, blank fields are Reserved and should not be accessed.

**Table 5. Register Map Bank 0 Table: User Space**

Name	Addr (0, Hex)	Access	Name	Addr (0, Hex)	Access	Name	Addr (0, Hex)	Access	Name	Addr (0, Hex)	Access
PRT0DR	00	RW	DBB20DR0	40	#	ASC10CR0	80	RW	RD12RI	C0	RW
PRT0IE	01	RW	DBB20DR1	41	W	ASC10CR1	81	RW	RD12SYN	C1	RW
PRT0GS	02	RW	DBB20DR2	42	RW	ASC10CR2	82	RW	RD12IS	C2	RW
PRT0DM2	03	RW	DBB20CR0	43	#	ASC10CR3	83	RW	RD12LT0	C3	RW
PRT1DR	04	RW	DBB21DR0	44	#	ASD11CR0	84	RW	RD12LT1	C4	RW
PRT1IE	05	RW	DBB21DR1	45	W	ASD11CR1	85	RW	RD12RO0	C5	RW
PRT1GS	06	RW	DBB21DR2	46	RW	ASD11CR2	86	RW	RD12RO1	C6	RW
PRT1DM2	07	RW	DBB21CR0	47	#	ASD11CR3	87	RW		C7	
PRT2DR	08	RW	DCB22DR0	48	#	ASC12CR0	88	RW	RD13RI	C8	RW
PRT2IE	09	RW	DCB22DR1	49	W	ASC12CR1	89	RW	RD13SYN	C9	RW
PRT2GS	0A	RW	DCB22DR2	4A	RW	ASC12CR2	8A	RW	RD13IS	CA	RW
PRT2DM2	0B	RW	DCB22CR0	4B	#	ASC12CR3	8B	RW	RD13LT0	CB	RW
PRT3DR	0C	RW	DCB23DR0	4C	#	ASD13CR0	8C	RW	RD13LT1	CC	RW
PRT3IE	0D	RW	DCB23DR1	4D	W	ASD13CR1	8D	RW	RD13RO0	CD	RW
PRT3GS	0E	RW	DCB23DR2	4E	RW	ASD13CR2	8E	RW	RD13RO1	CE	RW
PRT3DM2	0F	RW	DCB23CR0	4F	#	ASD13CR3	8F	RW		CF	
PRT4DR	10	RW	DBB30DR0	50	#	ASD20CR0	90	RW	CUR_PP	D0	RW
PRT4IE	11	RW	DBB30DR1	51	W	ASD20CR1	91	RW	STK_PP	D1	RW
PRT4GS	12	RW	DBB30DR2	52	RW	ASD20CR2	92	RW		D2	
PRT4DM2	13	RW	DBB30CR0	53	#	ASD20CR3	93	RW	IDX_PP	D3	RW
PRT5DR	14	RW	DBB31DR0	54	#	ASC21CR0	94	RW	MVR_PP	D4	RW
PRT5IE	15	RW	DBB31DR1	55	W	ASC21CR1	95	RW	MVW_PP	D5	RW
PRT5GS	16	RW	DBB31DR2	56	RW	ASC21CR2	96	RW	I2C_CFG	D6	RW
PRT5DM2	17	RW	DBB31CR0	57	#	ASC21CR3	97	RW	I2C_SCR	D7	#
	18		DCB32DR0	58	#	ASD22CR0	98	RW	I2C_DR	D8	RW
	19		DCB32DR1	59	W	ASD22CR1	99	RW	I2C_MSCR	D9	#
	1A		DCB32DR2	5A	RW	ASD22CR2	9A	RW	INT_CLR0	DA	RW
	1B		DCB32CR0	5B	#	ASD22CR3	9B	RW	INT_CLR1	DB	RW
	1C		DCB33DR0	5C	#	ASC23CR0	9C	RW	INT_CLR2	DC	RW
	1D		DCB33DR1	5D	W	ASC23CR1	9D	RW	INT_CLR3	DD	RW
	1E		DCB33DR2	5E	RW	ASC23CR2	9E	RW	INT_MSK3	DE	RW
	1F		DCB33CR0	5F	#	ASC23CR3	9F	RW	INT_MSK2	DF	RW
DBB00DR0	20	#	AMX_IN	60	RW		A0		INT_MSK0	E0	RW
DBB00DR1	21	W		61			A1		INT_MSK1	E1	RW
DBB00DR2	22	RW		62			A2		INT_VC	E2	RC
DBB00CR0	23	#	ARF_CR	63	RW		A3		RES_WDT	E3	W
DBB01DR0	24	#	CMP_CR0	64	#		A4		DEC_DH	E4	RC
DBB01DR1	25	W	ASY_CR	65	#		A5		DEC_DL	E5	RC
DBB01DR2	26	RW	CMP_CR1	66	RW		A6		DEC_CR0	E6	RW
DBB01CR0	27	#		67			A7		DEC_CR1	E7	RW
DCB02DR0	28	#		68		MUL1_X	A8	W	MUL0_X	E8	W
DCB02DR1	29	W		69		MUL1_Y	A9	W	MUL0_Y	E9	W
DCB02DR2	2A	RW		6A		MUL1_DH	AA	R	MUL0_DH	EA	R
DCB02CR0	2B	#		6B		MUL1_DL	AB	R	MUL0_DL	EB	R
DCB03DR0	2C	#	TMP_DR0	6C	RW	ACC1_DR1	AC	RW	ACC0_DR1	EC	RW
DCB03DR1	2D	W	TMP_DR1	6D	RW	ACC1_DR0	AD	RW	ACC0_DR0	ED	RW
DCB03DR2	2E	RW	TMP_DR2	6E	RW	ACC1_DR3	AE	RW	ACC0_DR3	EE	RW
DCB03CR0	2F	#	TMP_DR3	6F	RW	ACC1_DR2	AF	RW	ACC0_DR2	EF	RW
DBB10DR0	30	#	ACB00CR3	70	RW	RDI0RI	B0	RW		F0	
DBB10DR1	31	W	ACB00CR0	71	RW	RDI0SYN	B1	RW		F1	
DBB10DR2	32	RW	ACB00CR1	72	RW	RDI0IS	B2	RW		F2	
DBB10CR0	33	#	ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	
DBB11DR0	34	#	ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
DBB11DR1	35	W	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DBB11DR2	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
DBB11CR0	37	#	ACB01CR2	77	RW		B7		CPU_F	F7	RL
DCB12DR0	38	#	ACB02CR3	78	RW	RDI1RI	B8	RW		F8	
DCB12DR1	39	W	ACB02CR0	79	RW	RDI1SYN	B9	RW		F9	
DCB12DR2	3A	RW	ACB02CR1	7A	RW	RDI1IS	BA	RW		FA	
DCB12CR0	3B	#	ACB02CR2	7B	RW	RDI1LT0	BB	RW		FB	
DCB13DR0	3C	#	ACB03CR3	7C	RW	RDI1LT1	BC	RW		FC	
DCB13DR1	3D	W	ACB03CR0	7D	RW	RDI1RO0	BD	RW		FD	
DCB13DR2	3E	RW	ACB03CR1	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCB13CR0	3F	#	ACB03CR2	7F	RW		BF		CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed.

# Access is bit specific.



**Table 6. Register Map Bank 1 Table: Configuration Space**

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
PRT0DM0	00	RW	DBB20FN	40	RW	ASC10CR0	80	RW	RD12RI	C0	RW
PRT0DM1	01	RW	DBB20IN	41	RW	ASC10CR1	81	RW	RD12SYN	C1	RW
PRT0IC0	02	RW	DBB20OU	42	RW	ASC10CR2	82	RW	RD12IS	C2	RW
PRT0IC1	03	RW		43		ASC10CR3	83	RW	RD12LT0	C3	RW
PRT1DM0	04	RW	DBB21FN	44	RW	ASD11CR0	84	RW	RD12LT1	C4	RW
PRT1DM1	05	RW	DBB21IN	45	RW	ASD11CR1	85	RW	RD12RO0	C5	RW
PRT1IC0	06	RW	DBB21OU	46	RW	ASD11CR2	86	RW	RD12RO1	C6	RW
PRT1IC1	07	RW		47		ASD11CR3	87	RW		C7	
PRT2DM0	08	RW	DCB22FN	48	RW	ASC12CR0	88	RW	RD13RI	C8	RW
PRT2DM1	09	RW	DCB22IN	49	RW	ASC12CR1	89	RW	RD13SYN	C9	RW
PRT2IC0	0A	RW	DCB22OU	4A	RW	ASC12CR2	8A	RW	RD13IS	CA	RW
PRT2IC1	0B	RW		4B		ASC12CR3	8B	RW	RD13LT0	CB	RW
PRT3DM0	0C	RW	DCB23FN	4C	RW	ASD13CR0	8C	RW	RD13LT1	CC	RW
PRT3DM1	0D	RW	DCB23IN	4D	RW	ASD13CR1	8D	RW	RD13RO0	CD	RW
PRT3IC0	0E	RW	DCB23OU	4E	RW	ASD13CR2	8E	RW	RD13RO1	CE	RW
PRT3IC1	0F	RW		4F		ASD13CR3	8F	RW		CF	
PRT4DM0	10	RW	DBB30FN	50	RW	ASD20CR0	90	RW	GDI_O_IN	D0	RW
PRT4DM1	11	RW	DBB30IN	51	RW	ASD20CR1	91	RW	GDI_E_IN	D1	RW
PRT4IC0	12	RW	DBB30OU	52	RW	ASD20CR2	92	RW	GDI_O_OU	D2	RW
PRT4IC1	13	RW		53		ASD20CR3	93	RW	GDI_E_OU	D3	RW
PRT5DM0	14	RW	DBB31FN	54	RW	ASC21CR0	94	RW		D4	
PRT5DM1	15	RW	DBB31IN	55	RW	ASC21CR1	95	RW		D5	
PRT5IC0	16	RW	DBB31OU	56	RW	ASC21CR2	96	RW		D6	
PRT5IC1	17	RW		57		ASC21CR3	97	RW		D7	
	18		DCB32FN	58	RW	ASD22CR0	98	RW		D8	
	19		DCB32IN	59	RW	ASD22CR1	99	RW		D9	
	1A		DCB32OU	5A	RW	ASD22CR2	9A	RW		DA	
	1B			5B		ASD22CR3	9B	RW		DB	
	1C		DCB33FN	5C	RW	ASC23CR0	9C	RW		DC	
	1D		DCB33IN	5D	RW	ASC23CR1	9D	RW	OSC_GO_EN	DD	RW
	1E		DCB33OU	5E	RW	ASC23CR2	9E	RW	OSC_CR4	DE	RW
	1F			5F		ASC23CR3	9F	RW	OSC_CR3	DF	RW
DBB00FN	20	RW	CLK_CR0	60	RW		A0		OSC_CR0	E0	RW
DBB00IN	21	RW	CLK_CR1	61	RW		A1		OSC_CR1	E1	RW
DBB00OU	22	RW	ABF_CR0	62	RW		A2		OSC_CR2	E2	RW
	23		AMD_CR0	63	RW		A3		VLT_CR	E3	RW
DBB01FN	24	RW		64			A4		VLT_CMP	E4	R
DBB01IN	25	RW		65			A5			E5	
DBB01OU	26	RW	AMD_CR1	66	RW		A6			E6	
	27		ALT_CR0	67	RW		A7			E7	
DCB02FN	28	RW	ALT_CR1	68	RW		A8		IMO_TR	E8	W
DCB02IN	29	RW	CLK_CR2	69	RW		A9		ILO_TR	E9	W
DCB02OU	2A	RW		6A			AA		BDG_TR	EA	RW
	2B			6B			AB		ECO_TR	EB	W
DCB03FN	2C	RW	TMP_DR0	6C	RW		AC			EC	
DCB03IN	2D	RW	TMP_DR1	6D	RW		AD			ED	
DCB03OU	2E	RW	TMP_DR2	6E	RW		AE			EE	
	2F		TMP_DR3	6F	RW		AF			EF	
DBB10FN	30	RW	ACB00CR3	70	RW	RD10RI	B0	RW		F0	
DBB10IN	31	RW	ACB00CR0	71	RW	RD10SYN	B1	RW		F1	
DBB10OU	32	RW	ACB00CR1	72	RW	RD10IS	B2	RW		F2	
	33		ACB00CR2	73	RW	RD10LT0	B3	RW		F3	
DBB11FN	34	RW	ACB01CR3	74	RW	RD10LT1	B4	RW		F4	
DBB11IN	35	RW	ACB01CR0	75	RW	RD10RO0	B5	RW		F5	
DBB11OU	36	RW	ACB01CR1	76	RW	RD10RO1	B6	RW		F6	
	37		ACB01CR2	77	RW		B7		CPU_F	F7	RL
DCB12FN	38	RW	ACB02CR3	78	RW	RD11RI	B8	RW		F8	
DCB12IN	39	RW	ACB02CR0	79	RW	RD11SYN	B9	RW		F9	
DCB12OU	3A	RW	ACB02CR1	7A	RW	RD11IS	BA	RW	FLS_PR1	FA	RW
	3B		ACB02CR2	7B	RW	RD11LT0	BB	RW		FB	
DCB13FN	3C	RW	ACB03CR3	7C	RW	RD11LT1	BC	RW		FC	
DCB13IN	3D	RW	ACB03CR0	7D	RW	RD11RO0	BD	RW		FD	
DCB13OU	3E	RW	ACB03CR1	7E	RW	RD11RO1	BE	RW	CPU_SCR1	FE	#
	3F		ACB03CR2	7F	RW		BF		CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed.

# Access is bit specific.

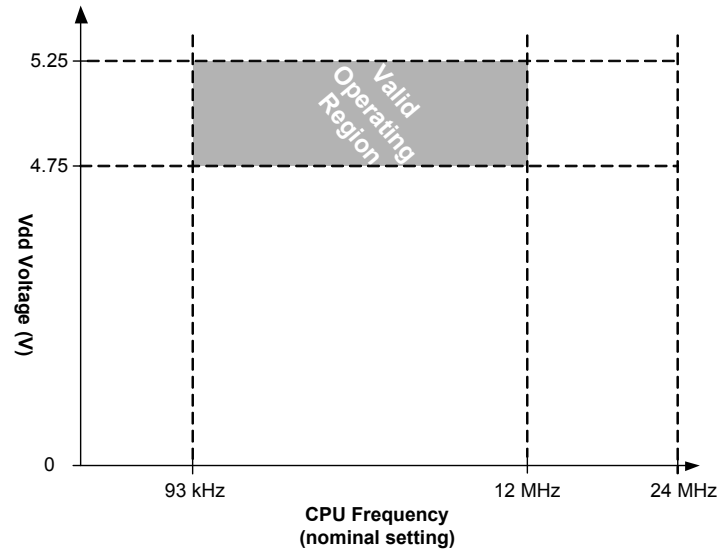


## Electrical Specifications

This section presents the DC and AC electrical specifications of the automotive CY8C29x66 PSoC device. For the most up to date electrical specifications, confirm that you have the most recent data sheet by visiting <http://www.cypress.com>.

Specifications are valid for  $-40\text{ }^{\circ}\text{C} \leq T_A \leq 125\text{ }^{\circ}\text{C}$  and  $T_J \leq 135\text{ }^{\circ}\text{C}$ , except where noted.

**Figure 5. Voltage versus CPU Frequency**



## Absolute Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

**Table 7. Absolute Maximum Ratings**

Symbol	Description	Min	Typ	Max	Units	Notes
T <sub>STG</sub>	Storage Temperature	–55	+25	+125	°C	Higher storage temperatures reduce data retention time. Recommended storage temperature is +25 °C ± 25 °C. Storage temperatures above 65 °C degrade reliability. Maximum combined storage and operational time at +125 °C is 7000 hours.
T <sub>BAKETEMP</sub>	Bake Temperature	–	125	See package label	°C	
T <sub>BAKETIME</sub>	Bake Time	See package label	–	72	Hours	
T <sub>A</sub>	Ambient Temperature with Power Applied	–40	–	+125	°C	
V <sub>dd</sub>	Supply Voltage on Vdd Relative to Vss	–0.5	–	+6.0	V	
V <sub>IO</sub>	DC Input Voltage	Vss – 0.5	–	Vdd + 0.5	V	
V <sub>IOZ</sub>	DC Voltage Applied to Tri-state	Vss – 0.5	–	Vdd + 0.5	V	
I <sub>MIO</sub>	Maximum Current into any Port Pin	–25	–	+25	mA	
ESD	Electro Static Discharge Voltage	2000	–	–	V	Human Body Model ESD.
LU	Latch up Current	–	–	200	mA	

## Operating Temperature

**Table 8. Operating Temperature**

Symbol	Description	Min	Typ	Max	Units	Notes
T <sub>A</sub>	Ambient Temperature	–40	–	+125	°C	
T <sub>J</sub>	Junction Temperature	–40	–	+135	°C	The temperature rise from ambient to junction is package specific. See <a href="#">Thermal Impedances on page 30</a> . The user must limit the power consumption to comply with this requirement.

## DC Electrical Characteristics

### DC Chip-Level Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 9. DC Chip-Level Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
V <sub>DD</sub>	Supply Voltage	4.75	–	5.25	V	
I <sub>DD</sub>	Supply Current	–	8	15	mA	Conditions are $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ , CPU=3 MHz, 48 MHz disabled. VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 0.366 kHz. Analog power = off.
I <sub>SB</sub>	Sleep (Mode) Current with POR, LVD, Sleep Timer, and WDT. <sup>[7]</sup>	–	6	16	μA	Conditions are with internal low speed oscillator active, $-40^{\circ}\text{C} \leq T_A \leq 55^{\circ}\text{C}$ . Analog power = off.
I <sub>SBH</sub>	Sleep (Mode) Current with POR, LVD, Sleep Timer, and WDT at high temperature <sup>[7]</sup>	–	6	100	μA	Conditions are with internal low speed oscillator active, $55^{\circ}\text{C} < T_A \leq 125^{\circ}\text{C}$ . Analog power = off.
I <sub>SBXTL</sub>	Sleep (Mode) Current with POR, LVD, Sleep Timer, WDT, and external crystal. <sup>[7]</sup>	–	8	18	μA	Conditions are with properly loaded, 1 μW max, 32.768 kHz crystal. $-40^{\circ}\text{C} \leq T_A \leq 55^{\circ}\text{C}$ . Analog power = off.
I <sub>SBXTLH</sub>	Sleep (Mode) Current with POR, LVD, Sleep Timer, WDT, and external crystal at high temperature. <sup>[7]</sup>	–	8	100	μA	Conditions are with properly loaded, 1 μW max, 32.768 kHz crystal. $55^{\circ}\text{C} < T_A \leq 125^{\circ}\text{C}$ . Analog power = off.
V <sub>REF</sub>	Reference Voltage (Bandgap)	1.25	1.3	1.35	V	

#### Note

7. Standby current includes all functions (POR, LVD, WDT, Sleep Timer) needed for reliable system operation. This must be compared with devices that have similar functions enabled.

### DC General Purpose I/O Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 10. DC GPIO Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
R <sub>PU</sub>	Pull up Resistor	4	5.6	8	k $\Omega$	
R <sub>PD</sub>	Pull down Resistor	4	5.6	8	k $\Omega$	
V <sub>OH</sub>	High Output Level	3.5	–	–	V	I <sub>OH</sub> = 10 mA, V <sub>dd</sub> = 4.75 to 5.25 V (maximum 40 mA on even port pins (for example, P0[2], P1[4]), maximum 40 mA on odd port pins (for example, P0[3], P1[5])). 80 mA maximum combined I <sub>OH</sub> budget.
V <sub>OL</sub>	Low Output Level	–	–	0.75	V	I <sub>OL</sub> = 25 mA, V <sub>dd</sub> = 4.75 to 5.25 V (maximum 100 mA on even port pins (for example, P0[2], P1[4]), maximum 100 mA on odd port pins (for example, P0[3], P1[5])). 150 mA maximum combined I <sub>OL</sub> budget.
I <sub>OH</sub>	High Level Source Current	10	–	–	mA	V <sub>OH</sub> $\geq$ V <sub>dd</sub> –1.0 V, see the limitations of the total current in the note for V <sub>OH</sub>
I <sub>OL</sub>	Low Level Sink Current	25	–	–	mA	V <sub>OL</sub> $\leq$ 0.75 V, see the limitations of the total current in the note for V <sub>OL</sub>
V <sub>IL</sub>	Input Low Level	–	–	0.8	V	
V <sub>IH</sub>	Input High Level	2.1	–		V	
V <sub>H</sub>	Input Hysteresis	–	60	–	mV	
I <sub>IL</sub>	Input Leakage (Absolute Value)	–	1	–	nA	Gross tested to 1 $\mu$ A.
C <sub>IN</sub>	Capacitive Load on Pins as Input	–	3.5	10	pF	Package and pin dependent. Temp = 25 $^{\circ}\text{C}$ .
C <sub>OUT</sub>	Capacitive Load on Pins as Output	–	3.5	10	pF	Package and pin dependent. Temp = 25 $^{\circ}\text{C}$ .

#### DC Low Power Comparator Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 12. DC Low Power Comparator Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{REFLPC}$	Low power comparator (LPC) reference voltage range	0.2	–	$V_{DD} - 1$	V	
$I_{SLPC}$	LPC supply current	–	10	40	$\mu\text{A}$	
$V_{OSLPC}$	LPC voltage offset	–	2.5	30	mV	

#### DC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 13. DC Analog Output Buffer Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{OSOB}$	Input Offset Voltage (Absolute Value)	–	3	18	mV	
$TCV_{OSOB}$	Input Offset Voltage Drift	–	+6	–	$\mu\text{V}/^{\circ}\text{C}$	
$V_{CMOB}$	Common-Mode Input Voltage Range	0.5	–	$V_{DD} - 1.0$	V	
$R_{OUTOB}$	Output Resistance	–	1	–	$\Omega$	
$V_{OHIGHOB}$	High Output Voltage Swing (Load = $32\Omega$ to $V_{DD}/2$ )	$0.5 \times V_{DD} + 1.1$	–	–	V	
$V_{OLOWOB}$	Low Output Voltage Swing (Load = $32\Omega$ to $V_{DD}/2$ )	–	–	$0.5 \times V_{DD} - 1.3$	V	
$I_{SOB}$	Supply Current Including Bias Cell (No Load) Power = Low Power = High	– –	1.1 2.6	5.1 8.8	mA mA	
$PSRR_{OB}$	Supply Voltage Rejection Ratio	–	64	–	dB	

### DC Analog Reference Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

The guaranteed specifications for RefHI and RefLO are measured through the analog continuous time PSoC blocks. The power levels for RefHI and RefLO refer to the analog reference control register. AGND is measured at P2[4] in AGND bypass mode. Each analog continuous time PSoC block adds a maximum of 10 mV additional offset error to guaranteed AGND specifications from the local AGND buffer. Reference control power can be set to medium or high unless otherwise noted.

**Note** Avoid using P2[4] for digital signaling when using an analog resource that depends on the Analog Reference. Some coupling of the digital signal may appear on the AGND.

**Table 14. DC Analog Reference Specifications**

Symbol	Description	Min	Typ	Max	Units
$V_{BG}$	Bandgap Voltage Reference	1.25	1.30	1.35	V
–	AGND = $V_{dd}/2$ <sup>[8]</sup>	$V_{dd}/2 - 0.02$	$V_{dd}/2$	$V_{dd}/2 + 0.02$	V
–	AGND = $2 \times \text{BandGap}$ <sup>[8]</sup>	2.4	2.6	2.8	V
–	AGND = P2[4] (P2[4] = $V_{dd}/2$ ) <sup>[8]</sup>	P2[4] – 0.02	P2[4]	P2[4] + 0.02	V
–	AGND = $\text{BandGap}$ <sup>[8]</sup>	1.23	1.3	1.37	V
–	AGND = $1.6 \times \text{BandGap}$ <sup>[8]</sup>	1.98	2.08	2.14	V
–	AGND Column to Column Variation (AGND = $V_{dd}/2$ ) <sup>[8]</sup>	0.035	0.000	0.035	V
–	RefHi = $V_{dd}/2 + \text{BandGap}$ <sup>[9]</sup>	$V_{dd}/2 + 1.15$	$V_{dd}/2 + 1.30$	$V_{dd}/2 + 1.45$	V
–	RefHi = $3 \times \text{BandGap}$ <sup>[9]</sup>	3.65	3.9	4.15	V
–	RefHi = $2 \times \text{BandGap} + \text{P2}[6]$ (P2[6] = 1.3 V) <sup>[9]</sup>	P2[6] + 2.4	P2[6] + 2.6	P2[6] + 2.8	V
–	RefHi = P2[4] + $\text{BandGap}$ (P2[4] = $V_{dd}/2$ ) <sup>[9]</sup>	P2[4] + 1.24	P2[4] + 1.30	P2[4] + 1.36	V
–	RefHi = P2[4] + P2[6] (P2[4] = $V_{dd}/2$ , P2[6] = 1.3 V) <sup>[9]</sup>	P2[4] + P2[6] – 0.1	P2[4] + P2[6]	P2[4] + P2[6] + 0.1	V
–	RefHi = $2 \times \text{BandGap}$ <sup>[9]</sup>	2.4	2.6	2.8	V
–	RefHi = $3.2 \times \text{BandGap}$ <sup>[9]</sup>	3.9	4.16	4.42	V
–	RefLo = $V_{dd}/2 - \text{BandGap}$ <sup>[9]</sup>	$V_{dd}/2 - 1.45$	$V_{dd}/2 - 1.3$	$V_{dd}/2 - 1.15$	V
–	RefLo = $\text{BandGap}$ <sup>[9]</sup>	1.15	1.30	1.45	V
–	RefLo = $2 \times \text{BandGap} - \text{P2}[6]$ (P2[6] = 1.3 V) <sup>[9]</sup>	2.4 – P2[6]	2.6 – P2[6]	2.8 – P2[6]	V
–	RefLo = P2[4] – $\text{BandGap}$ (P2[4] = $V_{dd}/2$ ) <sup>[9]</sup>	P2[4] – 1.45	P2[4] – 1.3	P2[4] – 1.15	V
–	RefLo = P2[4] – P2[6] (P2[4] = $V_{dd}/2$ , P2[6] = 1.3 V) <sup>[9]</sup>	P2[4] – P2[6] – 0.1	P2[4] – P2[6]	P2[4] – P2[6] + 0.1	V

### DC Analog PSoC Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 15. DC Analog PSoC Block Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$R_{CT}$	Resistor Unit Value (Continuous Time)	–	12.24	–	k $\Omega$	
$C_{SC}$	Capacitor Unit Value (Switch Cap)	–	80	–	fF	

#### Notes

8. This specification is only valid when CT Block Power = High. AGND tolerance includes the offsets of the local buffer in the PSoC block.
9. This specification is only valid when Ref Control Power = High.

### DC POR and LVD Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 16. DC POR and LVD Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{PPOR2}$	Vdd Value for PPOR Trip PORLEV[1:0] = 10b	–	4.55	4.70	V	Vdd must be greater than or equal to 2.5 V during startup, reset from the XRES pin, or reset from watchdog.
$V_{LVD6}$ $V_{LVD7}$	Vdd Value for LVD Trip VM[2:0] = 110b VM[2:0] = 111b	4.62 4.710	4.73 4.814	4.83 4.950	V V	

### DC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 17. DC Programming Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$I_{DDP}$	Supply Current During Programming or Verify	–	15	30	mA	
$V_{ILP}$	Input Low Voltage During Programming or Verify	–	–	0.8	V	
$V_{IHP}$	Input High Voltage During Programming or Verify	2.1	–	–	V	
$I_{ILP}$	Input Current when Applying $V_{ILP}$ to P1[0] or P1[1] During Programming or Verify	–	–	0.2	mA	Driving internal pull down resistor.
$I_{IHP}$	Input Current when Applying $V_{IHP}$ to P1[0] or P1[1] During Programming or Verify	–	–	1.5	mA	Driving internal pull down resistor.
$V_{OLV}$	Output Low Voltage During Programming or Verify	–	–	0.75	V	
$V_{OHV}$	Output High Voltage During Programming or Verify	3.5	–	Vdd	V	
Flash <sub>ENPB</sub>	Flash Endurance (per block) <sup>[10]</sup>	100	–	–	–	Erase/write cycles per block.
Flash <sub>ENT</sub>	Flash Endurance (total) <sup>[10, 11]</sup>	51,200	–	–	–	Erase/write cycles.
Flash <sub>DR</sub>	Flash Data Retention <sup>[12]</sup>	15	–	–	Years	

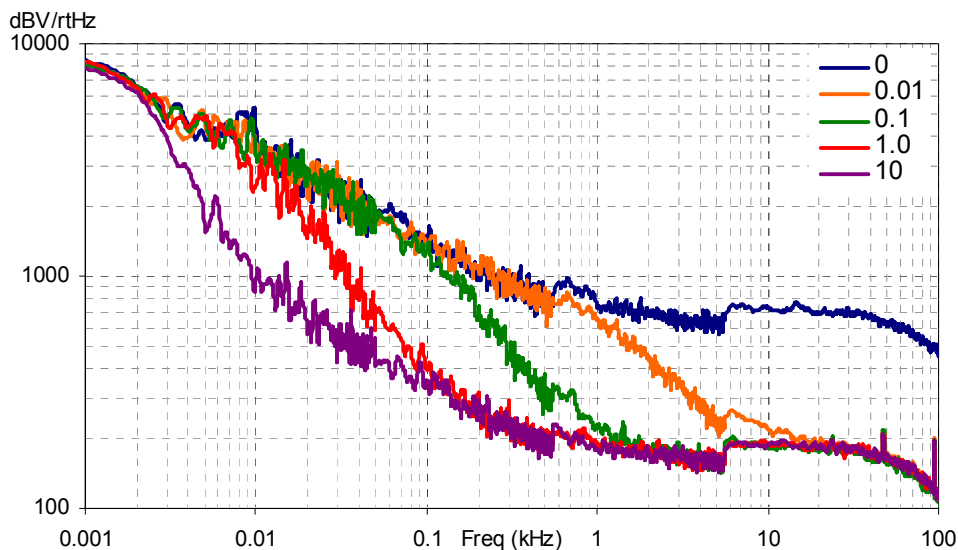
#### Notes

10. For the full temperature range, the user must employ a temperature sensor user module (FlashTemp) or other temperature sensor, and feed the result to the temperature argument before writing. Refer to the Flash APIs Application Note AN2015 at <http://www.cypress.com> under Application Notes for more information.
11. The maximum total number of allowed erase/write cycles is the minimum Flash<sub>ENPB</sub> value multiplied by the number of flash blocks in the device.
12. Flash data retention based on the use condition of  $\leq 7000$  hours at  $T_A \leq 125^{\circ}\text{C}$  and the remaining time at  $T_A \leq 65^{\circ}\text{C}$ .



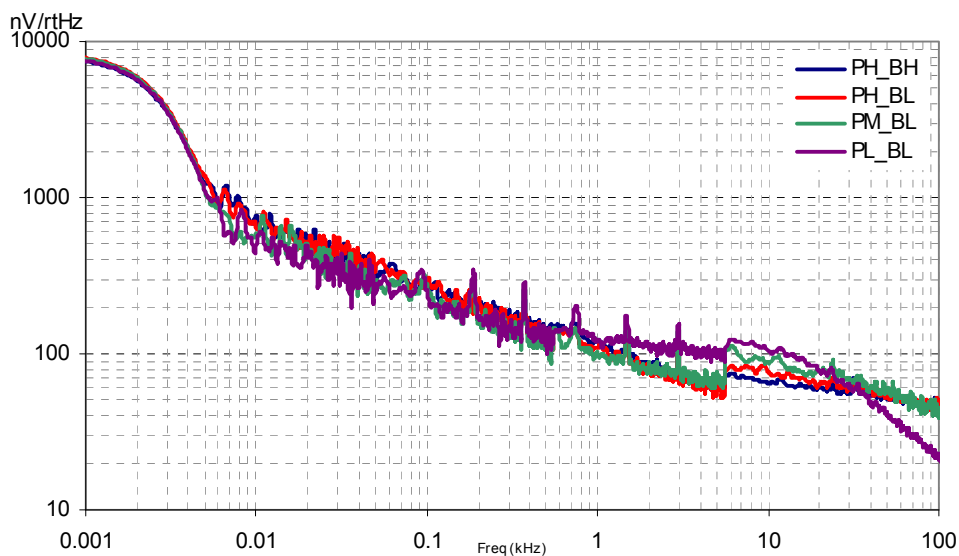
When bypassed by a capacitor on P2[4], the noise of the analog ground signal distributed to each block is reduced by a factor of up to 5 (14 dB). This is at frequencies above the corner frequency defined by the on-chip 8.1 k $\Omega$  resistance and the external capacitor.

**Figure 12. Typical AGND Noise with P2[4] Bypass**



At low frequencies, the opamp noise is proportional to  $1/f$ , power independent, and determined by device geometry. At high frequencies, increased power level reduces the noise spectrum level.

**Figure 13. Typical Opamp Noise**



### AC Low Power Comparator Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 21. AC Low Power Comparator Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$T_{RLPC}$	LPC response time	–	–	50	$\mu\text{s}$	$\geq 50\text{ mV}$ overdrive comparator reference set within $V_{REFLPC}$ .

### AC Digital Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ . Typical parameters apply to 5 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 22. AC Digital Block Specifications**

Function	Description	Min	Typ	Max	Units	Notes
All Functions	Maximum Block Clocking Frequency	–	–	$24.96^{[13]}$	MHz	
Timer	Capture Pulse Width	$50^{[15]}$	–	–	ns	
	Maximum Frequency, No Capture	–	–	$24.96^{[13]}$	MHz	
	Maximum Frequency, With Capture	–	–	$24.96^{[13]}$	MHz	
Counter	Enable Pulse Width	$50^{[15]}$	–	–	ns	
	Maximum Frequency, No Enable Input	–	–	$24.96^{[13]}$	MHz	
	Maximum Frequency, Enable Input	–	–	$24.96^{[13]}$	MHz	
Dead Band	Kill Pulse Width:					
	Asynchronous Restart Mode	20	–	–	ns	
	Synchronous Restart Mode	$50^{[15]}$	–	–	ns	
	Disable Mode	$50^{[15]}$	–	–	ns	
	Maximum Frequency	–	–	$24.96^{[13]}$	MHz	
CRCPRS (PRS Mode)	Maximum Input Clock Frequency	–	–	$24.96^{[13]}$	MHz	
CRCPRS (CRC Mode)	Maximum Input Clock Frequency	–	–	$24.96^{[13]}$	MHz	
SPIM	Maximum Input Clock Frequency	–	–	$4.16^{[13]}$	MHz	Maximum data rate is 2.08 Mbps due to $2 \times$ over clocking.
SPIS	Maximum Input Clock Frequency	–	–	$2.08^{[13]}$	MHz	
	Width of SS_ Negated Between Transmissions	$50^{[15]}$	–	–	ns	
Transmitter	Maximum Input Clock Frequency	–	–	$8.32^{[13]}$	MHz	Maximum baud rate at 1.04 Mbaud due to $8 \times$ over clocking.
Receiver	Maximum Input Clock Frequency	–	–	$24.96^{[13]}$	MHz	Maximum baud rate at 3.12 Mbaud due to $8 \times$ over clocking.

**Note**

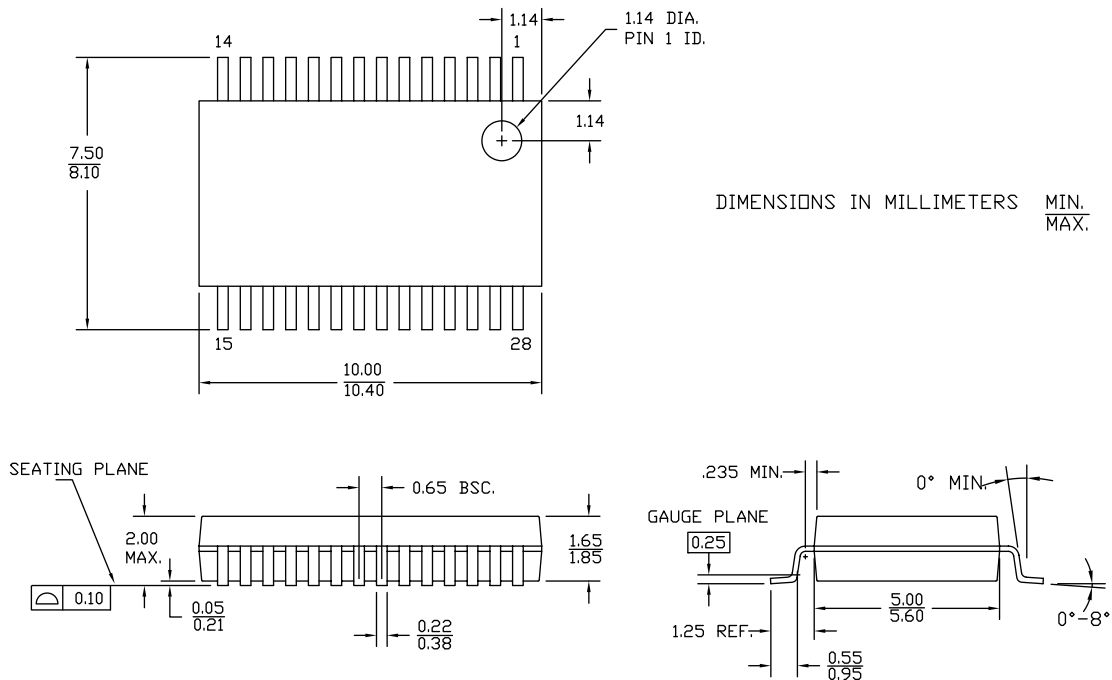
15. 50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).

## Packaging Information

This section illustrates the packaging specifications for the automotive CY8C29x66 PSoC device, along with the thermal impedances and solder reflow for each package and the typical package capacitance on crystal pins.

**Important Note** Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the emulator pod drawings at <http://www.cypress.com>.

**Figure 15. 28-pin SSOP (210 Mils)**



51-85079 \*F

## Development Tool Selection

This section presents the development tools available for the CY8C29x66 family.

### Software

#### *PSoC Designer*

At the core of the PSoC development software suite is PSoC Designer. Utilized by thousands of PSoC developers, this robust software has been facilitating PSoC designs for years. PSoC Designer is available free of charge at <http://www.cypress.com>. PSoC Designer comes with a free C compiler.

#### *PSoC Programmer*

Flexible enough to be used on the bench in development, yet suitable for factory programming, PSoC Programmer works either as a standalone programming application or it can operate directly from PSoC Designer. PSoC Programmer software is compatible with both PSoC ICE-Cube In-Circuit Emulator and PSoC MiniProg. PSoC programmer is available free of charge at <http://www.cypress.com>.

### Development Kits

All development kits can be purchased from the Cypress Online Store. The online store also has the most up to date information on kit contents, descriptions, and availability.

#### *CY3215-DK Basic Development Kit*

The CY3215-DK is for prototyping and development with PSoC Designer. This kit supports in-circuit emulation and the software interface allows users to run, halt, and single step the processor and view the contents of specific memory locations. Advanced emulation features are also supported through PSoC Designer. The kit includes:

- ICE-Cube Unit
- 28-pin PDIP Emulation Pod for CY8C29466-24PXI
- 28-pin CY8C29466-24PXI PDIP PSoC Device Samples (two)
- PSoC Designer Software CD
- ISSP Cable
- MiniEval Socket Programming and Evaluation board
- Backward Compatibility Cable (for connecting to legacy Pods)
- Universal 110/220 Power Supply (12 V)
- European Plug Adapter
- USB 2.0 Cable
- Getting Started Guide
- Development Kit Registration form

### Evaluation Tools

All evaluation tools can be purchased from the Cypress Online Store. The online store also has the most up to date information on kit contents, descriptions, and availability.

#### *CY3210-PSoCEval1*

The CY3210-PSoCEval1 kit features an evaluation board and the MiniProg1 programming unit. The evaluation board includes an LCD module, potentiometer, LEDs, an RS-232 port, and plenty of breadboarding space to meet all of your evaluation needs. The kit includes:

- Evaluation Board with LCD Module
- MiniProg Programming Unit
- 28-pin CY8C29466-24PXI PDIP PSoC Device Sample (2)
- PSoC Designer Software CD
- Getting Started Guide
- USB 2.0 Cable

#### *CY3210-29X66 Evaluation Pod (EvalPod)*

PSoC EvalPods are pods that connect to the ICE In-Circuit Emulator (CY3215-DK kit) to allow debugging capability. They can also function as a standalone device without debugging capability. The EvalPod has a 28-pin DIP footprint on the bottom for easy connection to development kits or other hardware. The top of the EvalPod has prototyping headers for easy connection to the device's pins. CY3210-29X66 provides evaluation of the CY8C29x66 PSoC device family.

### Device Programmers

All device programmers can be purchased from the Cypress Online Store.

#### *CY3210-MiniProg1*

The CY3210-MiniProg1 kit allows a user to program PSoC devices via the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC via a provided USB 2.0 cable. The kit includes:

- MiniProg Programming Unit
- MiniEval Socket Programming and Evaluation Board
- 28-pin CY8C29466-24PXI PDIP PSoC Device Sample
- PSoC Designer Software CD
- Getting Started Guide
- USB 2.0 Cable

## Reference Information

### Acronyms Used

The following table lists the acronyms that are used in this document.

**Table 32. Acronyms**

Acronym	Description	Acronym	Description
AC	alternating current	IMO	internal main oscillator
ADC	analog-to-digital converter	I/O	input/output
API	application programming interface	IPOR	imprecise power on reset
CPU	central processing unit	LSb	least-significant bit
CT	continuous time	LVD	low voltage detect
DAC	digital-to-analog converter	MSb	most-significant bit
DC	direct current	PC	program counter
ECO	external crystal oscillator	PLL	phase-locked loop
EEPROM	electrically erasable programmable read-only memory	POR	power on reset
FSR	full scale range	PPOR	precision power on reset
GPIO	general purpose IO	PSoC	Programmable System-on-Chip
GUI	graphical user interface	PWM	pulse width modulator
HBM	human body model	SC	switched capacitor
ICE	in-circuit emulator	SRAM	static random access memory
ILO	internal low speed oscillator		

### Units of Measure

The following table lists the units of measure that are used in this section.

**Table 33. Units of Measure**

Symbol	Unit of Measure	Symbol	Unit of Measure
°C	degree Celsius	μVrms	microvolts root-mean-square
dB	decibels	μW	microwatt
fF	femto farad	mA	milliampere
Hz	hertz	ms	millisecond
KB	1024 bytes	mV	millivolt
Kbit	1024 bits	nA	nanoampere
kHz	kilohertz	ns	nanosecond
kΩ	kilohm	nV	nanovolt
Mbaud	megabaud	Ω	ohm
Mbps	megabits per second	pA	picoampere
MHz	megahertz	pF	picofarad
MΩ	megaohm	pp	peak-to-peak
μA	microampere	ppm	parts per million
μF	microfarad	ps	picosecond
μH	microhenry	sps	samples per second
μs	microsecond	σ	sigma: one standard deviation
μV	microvolt	V	volt

### Numeric Naming

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, '01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or '0x' are decimal.

## Document History Page

Document Title: CY8C29466, CY8C29666, Automotive – Extended Temperature PSoC® Programmable System-on-Chip Document Number: 38-12026				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	228771	06/01/2004	SFV	First release of the CY8C29x66 automotive PSoC device data sheet.
*A	271452	See ECN	HMT	Update per SFV memo. Input changes from MWR, including removing SMP.
*B	288029	See ECN	HMT	Add Reflow Peak Temp. table. Update PSoC Characteristics table. Update characterization data.
*C	473829	See ECN	HMT	Update PSoC Characteristics table. Update characterization data. Update Storage Temperature for extended temperature devices. Fix error in Register Bank 0/1. Update CY color, logo and copyright.
*D	602219	See ECN	HMT	Add Low Power Comparator (LPC) AC/DC electrical spec. tables. Add CY8C20x34 to PSoC Device Characteristics table. Update Technical Training Modules paragraph. Add ISSP note to pinout tables.
*E	2101387	See ECN	AESA	Post to <a href="http://www.cypress.com">www.cypress.com</a>
*F	2545030	07/29/08	YARA	Added note to DC Analog Reference Specification table and Ordering Information
*G	2663861	02/24/09	PRKA / AESA	Updated template Removed CY8C29666-12PVXE and CY8C29666-12PVXET and related package information Updated PSoC Designer and Getting Started sections
*H	2756235	08/26/09	BTK/AESA	Changed title. Updated Features section. Updated text of PSoC Functional Overview section. Updated Getting Started section. Made corrections and minor text edits to Pinouts section. Changed the name of some sections for added clarity. Improved formatting of the register tables. Added clarifying comments to some electrical specifications. Changed T <sub>RAMP</sub> specification per MASJ input. Fixed all AC specifications to conform to a ±4% IMO accuracy. Made other miscellaneous minor text edits. Deleted some non-applicable or redundant information. Added a footnote to clarify that 8 of the 12 analog inputs are regular and the other 4 are direct SC block connections. Added Development Tool Selection section. Improved the bookmark structure. Changed the T <sub>ROB</sub> , T <sub>SOB</sub> , V <sub>IHP</sub> , V <sub>OHIGHOB</sub> , V <sub>OSOB</sub> , V <sub>OSOA</sub> , C <sub>INOA</sub> , V <sub>OHIGHOA</sub> , V <sub>OLOWOA</sub> , I <sub>SOA</sub> , Jitter24M1P, TRiseF, and DC POR and LVD specifications according to MASJ directives.
*I	2822792	12/07/2009	BTK/AESA	Added T <sub>PRGH</sub> , T <sub>PRGC</sub> , I <sub>OL</sub> , I <sub>OH</sub> , F <sub>32KU</sub> , DC <sub>ILO</sub> , and T <sub>POWERUP</sub> electrical specifications. Updated the text of footnote 10. Added maximum values and updated typical values for T <sub>ERASEB</sub> and T <sub>WRITE</sub> electrical specifications. Replaced T <sub>RAMP</sub> electrical specification with SR <sub>POWERUP</sub> electrical specification. Added "Contents" on page 2. This revision fixes CDT 63984.
*J	2888007	03/30/2010	NJF	Updated Cypress website links. Added T <sub>BAKETEMP</sub> and T <sub>BAKETIME</sub> parameters in <a href="#">Absolute Maximum Ratings</a> Updated <a href="#">Packaging Information</a> . Updated <a href="#">Development Kits</a> and <a href="#">Evaluation Tools</a> . Removed Third Party Tools and Build a PSoC Emulator into your Board. Updated <a href="#">Ordering Code Definitions</a> . Updated links in <a href="#">Sales, Solutions, and Legal Information</a> .
*K	3440253	11/16/2011	MYKT_UKR	Added part number CY8C29666-12PVXE to the <a href="#">Ordering Information</a> table. Added 48-pin part information to <a href="#">Pinouts</a> , <a href="#">Thermal Impedances</a> , and <a href="#">Capacitance on Crystal Pins</a> sections. Updated <a href="#">Accessories (Emulation and Programming)</a> section. Updated <a href="#">Solder Reflow Specifications</a> section. Included 48-Pin (300-Mil) SSOP spec to <a href="#">Packaging Information</a> section.
*L	3537225	02/28/2011	VIVG	No technical updates.